## **Amendments to the Claims**

- 1. (currently amended) Décor paper for laminate flooring, having a décor and comprising conductive carbon having an average particle size of less than 1000 nm, wherein the décor paper has a paper weight between 10 g/m² and 50 g/m² and is impregnated with a resin/acrylate mixture.
- 2. (currently amended) Décor paper according to claim 1, wherein the resin is further comprising a urea resin and/or a melamine resin and/or an acrylate resin.
- 3. (previously presented) Décor paper according to claim 1, further comprising abrasion-resistant particles.
  - 4. cancelled
- 5. (previously presented) Décor paper according to claim 1, wherein the carbon has an average particle size of less than 500 nm.
  - cancelled
- 7. (previously presented) A panel for flooring, comprising a carrier board and a décor paper according to claim 1 supported by the carrier board and forming a decorative top surface of the panel.
- 8. (currently amended) A panel according to claim 1, further comprising abrasion-resistant particles applied on the décor paper, and wherein the décor paper has a higher electrical conductivity higher than any other papers used in the manufacture of the panel.
  - 9. cancelled

- 10. (previously presented) A panel according to claim 1, comprising a counter-acting paper on the underside of the carrier board.
- 11. (previously presented) A panel according to claim 1, wherein the carrier board is made from HDF.
- 12. (previously presented) A panel according to claim 1, comprising coupling elements on its sides.
- 13. (previously presented) Décor paper according to claim 1, wherein the carbon has an average particle size of less than 1 nm.
- 14. (currently amended) A panel according to claim 7, wherein the carbon with has an average particle size of less than 500 nm.

## 15-17. cancelled

- 18. (currently amended) A panel according to claim <del>17</del> <u>8</u>, wherein the abrasion-resistant particles comprise corundum particles.
- 19. (currently amended) A panel according to claim <del>18</del> 7, wherein the carrier board is made from HDF.